

L Number	Hits	Search Text	DB	Time stamp
-	106939	(handl\$3 support\$3 product bond\$3) near (wafer substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:21
-	69122	(handl\$3 support\$3 product bond\$3) adj (wafer substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 15:45
-	5036	((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 15:52
-	594	((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 17:42
-	460	((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 15:57
-	206	((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 16:13
-	43	((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) near (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 17:08
-	10	interlocking adj wafers	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 17:14
-	13	lock near key near (wafer substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 17:38
-	38	interlocking adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 17:15

-	2131	((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 17:41
-	1372	((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 17:42
-	273	((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 17:42
-	32	((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:33
-	26	((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:33
-	7	((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3)) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:32
-	0	(interlocking adj wafers) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:32
-	0	(lock near key near (wafer substrate)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:32

-	1	(interlocking adj substrate) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:32
-	27	(((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) (((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) (((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) near (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) ((interlocking adj substrate) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:34

-	1	<pre> ((((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) (((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) (((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) near (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) ((interlocking adj substrate) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical)))) not (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) </pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:34
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-	2	(((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) near (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (MEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:42
-	15	(US-5370301-\$ or US-5514906-\$ or US-5753133-\$ or US-5959516-\$ or US-4762387-\$ or US-4966446-\$ or US-6143583-\$ or US-6277666-\$ or US-6291875-\$ or US-6392144-\$ or US-6535663-\$.did. or (US-20020037665-\$ or US-20010002872-\$ or US-20030034870-\$.did. or (US-20020037598-\$.did.	USPAT; US-PGPUB; DERWENT	2003/06/23 18:42

-	20	<p>(((((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate))) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) (((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) (((handl\$3 support\$3 product bond\$3) adj (wafer substrate)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) same (mechanical\$2 physical\$2) near (engag\$3 interlock\$3 interlink\$3 coupl\$3 join\$3 link\$3 lock\$3 hook\$3 connect\$3 interconnect\$3))) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) with (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and (limit\$3 reduc\$3 eliminat\$3 stop\$4 prevent\$3 lessen\$3 diminish\$3) near (lateral "side-to-side" sideways side (back near forth) horizontal movement motion mov\$3)) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) ((interlocking adj substrate) and ((handl\$3 support\$3 product bond\$3) near (wafer substrate)) and (OMEMS MEMS microelectromechanical "micro-electro-mechanical" micro adj electro adj mechanical))) not ((US-5370301-\$ or US-5514906-\$ or US-5753133-\$ or US-5959516-\$ or US-4762387-\$ or US-4966446-\$ or US-6143583-\$ or US-6277666-\$ or US-6291875-\$ or US-6392144-\$ or US-6535663-\$).did. or (US-20020037665-\$ or US-20010002872-\$ or US-20030034870-\$).did. or (US-20020037598-\$).did.)</p>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 18:43
-	137	etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:26
-	104	(etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and etch\$3 with (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:32

-	2	("6392144").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/24 14:07
-	1	((("6392144").PN.) and thermal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:33
-	1	((("6392144").PN.) and heat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:36
-	1	((("6392144").PN.) and insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:39
-	4	((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and etch\$3 with (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and thermal adj contact	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:45
-	0	((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and etch\$3 with (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and disc adj drive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:43
-	1	((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and disc adj drive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:43
-	0	((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and thermal adj contact not ((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and etch\$3 with (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and thermal adj contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:55
-	12	((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and actuator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:56
-	12	((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and actuator) ((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and microactuator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:56
-	3	((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and microactuator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 05:56

-	9	((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and actuator) not ((etch\$3 same (alignment aligning align) with (feature groove post hole peg ridge trench) same (handl\$3 support\$3 bond\$3) near (wafer substrate)) and microactuator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/30 06:01
-	421	MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:05
-	397	(MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 18:08
-	221	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 same etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 18:09
-	199	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 with etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 18:09
-	81	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 near etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 18:09
-	38	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 adj etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:00
-	321	align\$4 and (MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:00
-	308	align\$4 and ((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:00
-	161	align\$4 and (((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 same etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:00
-	143	align\$4 and (((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 with etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:00
-	56	align\$4 and (((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 near etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:01
-	24	align\$4 and (((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 adj etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:01

-	82	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:06
-	76	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:06
-	59	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 same etch\$3) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:06
-	54	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 with etch\$3) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:06
-	31	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 near etch\$3) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:06
-	9	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 adj etch\$3) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:06
-	6	(align\$4 and ((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 adj etch\$3))) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:08
-	3	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 adj etch\$3) and handle adj wafer NOT ((align\$4 and ((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 adj etch\$3))) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:09
-	22	((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 near etch\$3) and handle adj wafer NOT ((MEMS and ((handle support\$3) adj (wafer substrate)) and releas\$5) and etch\$3) and (releas\$5 adj etch\$3) and handle adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/17 19:09
-	26585	etch\$3 near through	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/24 14:08
-	19294	etch\$3 adj through	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/24 14:08
-	9095	through adj etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/24 14:10
-	26585	(etch\$3 adj through) (through adj etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/24 14:10

-	24	((etch\$3 adj through) (through adj etch\$3)) same (handle product) adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/24 14:11
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